SCBS104C - FEBRUARY 1991 - REVISED JANUARY 1997

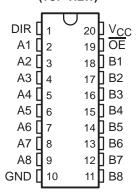
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

description

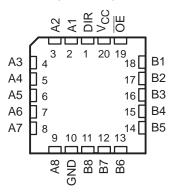
The 'ABT640 bus transceivers are designed for asynchronous communication between data buses. These devices transmit inverted data from the A bus to the B bus or from the B bus to the A bus, depending on the level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54ABT640 . . . J PACKAGE SN74ABT640 . . . DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT640 . . . FK PACKAGE (TOP VIEW)



The SN54ABT640 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT640 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INP	UTS	ODEDATION				
OE	DIR	OPERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	Χ	Isolation				

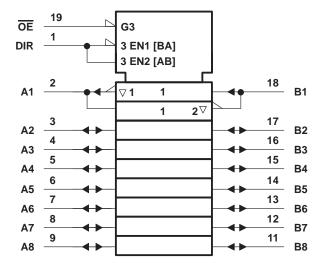


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

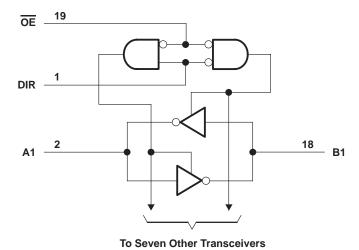


logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SCBS104C - FEBRUARY 1991 - REVISED JANUARY 1997

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	-0.5 V to 7 V
Input voltage range, V _I (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	. $-0.5\ V$ to $5.5\ V$
Current into any output in the low state, IO: SN54ABT640	96 mA
SN74ABT640	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DB package	115°C/W
DW package	97°C/W
N package	67°C/W
PW package	128°C/W
Storage temperature range, T _{sta}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54A	BT640	SN74A	BT640	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	EN	2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
٧ _I	Input voltage		0 <	Vcc	0	VCC	V
loh	High-level output current		Ć)	-24		-32	mA
loL	Low-level output current		200	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q.	5		5	ns/V
T _A	Operating free-air temperature		– 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

SN54ABT640, SN74ABT640 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS104C - FEBRUARY 1991 - REVISED JANUARY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	A or B ports IOZH	TEST CON	IDITIONS	Т	A = 25°C	;	SN54A	BT640	SN74A	BT640	UNIT
FAI	KAMETEK	TEST CON	IDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\ \/a		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				v
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
Voi		V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.55		0.55			V
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V
V _{hys}					100						mV
١,	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μΑ
''	A or B ports	VCC = 3.5 V,	A1 = ACC 01 QIAD			±100		±100		±100	μΑ
lozh‡		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			50		50		50	μΑ
lozL [‡]		$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$			-50		– 50		-50	μΑ
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	1	<u> </u>		±100	μΑ
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	27900	50		50	μА
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	- 50	-180	-50	-180	mA
		V _{CC} = 5.5 V,	Outputs high		5	250		250		250	μΑ
Icc	A or B ports	$I_{O} = 0$,	Outputs low		24	30		30		30	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ
	Data inputa	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	
ΔICC¶	Data inputs	Other inputs at VCC or GND	Outputs disabled			0.05		0.05		0.05	mA
ΔICC¶	Control inputs	$V_{CC} = 5.5 \text{ V}$, One inpute other inputs at V_{CC} or				1.5		1.5		1.5	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			7						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V A = 25°C	', ;	SN54A	BT640	SN74ABT640		UNIT
	(INFOT)	(001701)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	1	2.7	4.2	1	5	1	4.9	ns
^t PHL		BOIA	1.5	2.7	4.3	1.5	5	1.5	4.9	115
^t PZH	ŌĒ	A or B	1.5	3.7	4.9	1.5	5.9	1.5	5.8	
^t PZL	OE	A or B	1.3	5	5.9	1.3	7.4	1.3	7.3	ns
^t PHZ	ŌĒ	A or B	2.5	4.1	6.5	2.5	6.9	2.5	6.8	ns
^t PLZ	OE		2	3.3	5.3	2 2	5.6	2	5.5	115

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



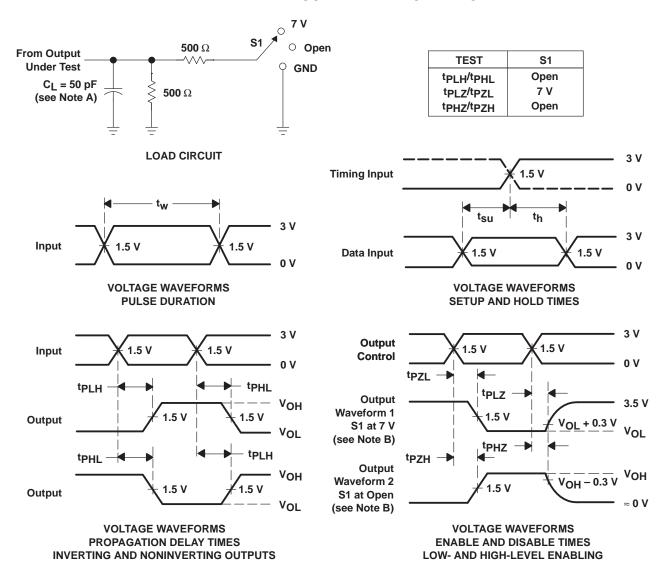
[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Ω} = 50 Ω , $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com

11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
	. ,					(4)	(5)		. ,
SN74ABT640DBR	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB640
SN74ABT640DBR.B	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB640
SN74ABT640DW	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT640
SN74ABT640DW.B	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT640
SN74ABT640DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT640
SN74ABT640DWR.B	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT640
SN74ABT640N	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT640N
SN74ABT640N.B	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT640N
SN74ABT640NSR	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT640
SN74ABT640NSR.B	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT640
SN74ABT640PW	Active	Production	TSSOP (PW) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB640
SN74ABT640PW.B	Active	Production	TSSOP (PW) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB640
SN74ABT640PWR	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB640
SN74ABT640PWR.B	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB640

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2025

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

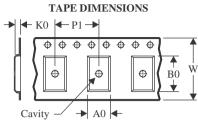
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 23-Jul-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

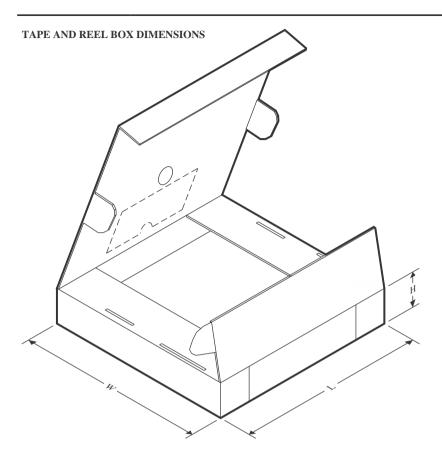
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT640DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT640DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ABT640NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ABT640PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

www.ti.com 23-Jul-2025



*All dimensions are nominal

7 till dillitoriolorio di o riorriiridi							
Device Package Type		Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT640DBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74ABT640DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74ABT640NSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74ABT640PWR	TSSOP	PW	20	2000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

www.ti.com 23-Jul-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT640DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT640DW.B	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT640N	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT640N.B	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT640PW	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74ABT640PW.B	PW	TSSOP	20	70	530	10.2	3600	3.5

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025